

# MT6015S5

## 60V Complementary Power MOSFET

### Features

- N-Channel  
60V/35A,  
 $R_{DS(ON)}=13m\Omega$  @  $V_{GS}=10V$   
 $R_{DS(ON)}=15m\Omega$  @  $V_{GS}=4.5V$
- P-Channel  
-60V/-34A,  
 $R_{DS(ON)}=26m\Omega$  @  $V_{GS}=10V$   
 $R_{DS(ON)}=33m\Omega$  @  $V_{GS}=4.5V$
- RoHS Compliant

### General Description

This complementary MOSFET device is produced using Mos-tech's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

### Applications

- DC-DC converter
- Power management
- LCD backlight inverter

### Absolute Maximum Ratings

$T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	N-CH	P-CH	Units
V <sub>DSS</sub>	Drain-Source Voltage	60	-60	V
V <sub>GSS</sub>	Gate-Source Voltage	±20	±20	V
I <sub>D</sub>	Drain Current   - Continuous			

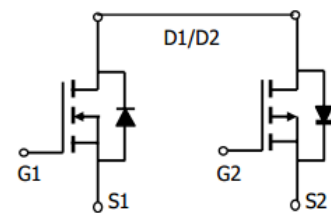
### Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	79	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	41	$^\circ\text{C/W}$



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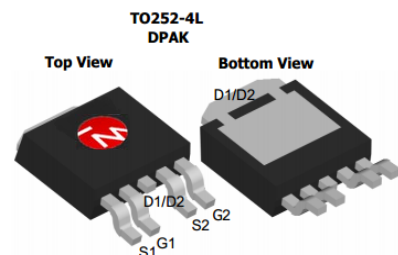
<http://www.mtsemi.com>



N-channel

P-channel

### MARKING DIAGRAM & PIN ASSIGNMENT



**Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units
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**Drain-Source Avalanche Ratings** (Note 1)

$W_{DSS}$	Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 30\text{ V}, I_D = 4.5\text{ A}$	N-CH			35	mJ
$I_{AR}$	Maximum Drain-Source Avalanche Current		N-CH			22	A

**Off Characteristics**

$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ $V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	N-CH P-CH	60 -60			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , Referenced to $25^\circ\text{C}$ $I_D = -250\text{ }\mu\text{A}$ , Referenced to $25^\circ\text{C}$	N-CH P-CH		59 -47		mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V}$ $V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}$	N-CH P-CH			1 -1	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$ $V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	N-CH P-CH			+100 -100	nA

**On Characteristics** (Note 2)

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ $V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$	N-CH P-CH	1 -1	1.5 -1.7	2.5 -2.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , Referenced to $25^\circ\text{C}$ $I_D = -250\text{ }\mu\text{A}$ , Referenced to $25^\circ\text{C}$	N-CH P-CH		-5.6 4		mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 3.0\text{ A}$ $V_{GS} = 4.5\text{ V}, I_D = 2.0\text{ A}$	N-CH		13 15	26 30	m $\Omega$
		$V_{GS} = -10\text{ V}, I_D = -3.0\text{ A}$ $V_{GS} = -4.5\text{ V}, I_D = -2.0\text{ A}$	P-CH		26 33	35 46	
$I_{D(on)}$	On-State Drain Current	$V_{GS} = 10\text{ V}, V_{DS} = 5\text{ V}$ $V_{GS} = -10\text{ V}, V_{DS} = -5\text{ V}$	N-CH P-CH	35 -34			A
$g_{FS}$	Forward Transconductance	$V_{DS} = 10\text{ V}, I_D = 4.5\text{ A}$ $V_{DS} = -5\text{ V}, I_D = -3.5\text{ A}$	N-CH P-CH		15 10		S

**Dynamic Characteristics**

$C_{iss}$	Input Capacitance	N-CH $V_{DS} = 55\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	N-CH P-CH		690 800		pF
$C_{oss}$	Output Capacitance	P-CH	N-CH P-CH		88 96		pF
$C_{rss}$	Reverse Transfer Capacitance	$V_{DS} = -55\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	N-CH P-CH		38 40		pF

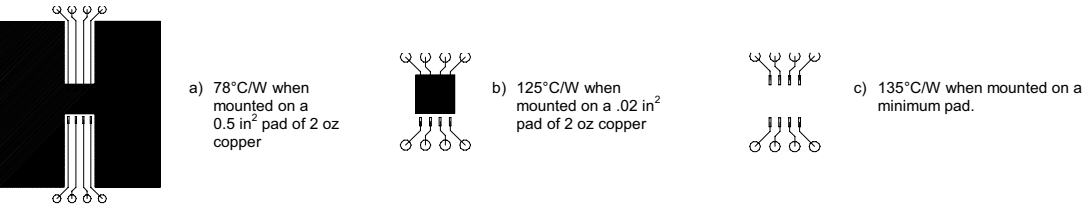
**Switching Characteristics** (Note 2)

$t_{d(on)}$	Turn-On Delay Time	N-CH $V_{DD} = 30\text{ V}, I_D = 1\text{ A},$ $V_{GS} = 10\text{ V}, R_{GEN} = 6\text{ }\Omega$	N-CH P-CH		15 7	25 17	ns
$t_r$	Turn-On Rise Time		N-CH P-CH		9 12	22 26	ns
$t_{d(off)}$	Turn-Off Delay Time	P-CH $V_{DD} = -60\text{ V}, I_D = -1\text{ A},$ $V_{GS} = -10\text{ V}, R_{GEN} = 6\text{ }\Omega$	N-CH P-CH		19 19	42 37	ns
$t_f$	Turn-Off Fall Time		N-CH P-CH		8 12	18 25	ns
$Q_g$	Total Gate Charge	N-CH $V_{DS} = 60\text{ V}, I_D = 4.5\text{ A}, V_{GS} = 10\text{ V}$	N-CH P-CH		15.5 18	22 24	nC
$Q_{gs}$	Gate-Source Charge	P-CH	N-CH P-CH		2.6 2.7		nC
$Q_{gd}$	Gate-Drain Charge	$V_{DS} = -60\text{ V}, I_D = -3.5\text{ A}, V_{GS} = -10\text{ V}$	N-CH P-CH		2.7 3.3		nC

Electrical Characteristics (continued)  $T_A = 25^{\circ}\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>							
$I_S$	Maximum Continuous Drain-Source Diode Forward Current		N-CH P-CH			1.3 -1.3	A
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 1.3\text{ A}$ (Note 2) $V_{GS} = 0\text{ V}, I_S = -1.3\text{ A}$ (Note 2)	N-CH P-CH		0.8 -0.8	1.1 -1.1	V

**Notes:**  
1.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%

## Typical Characteristics: P-CH

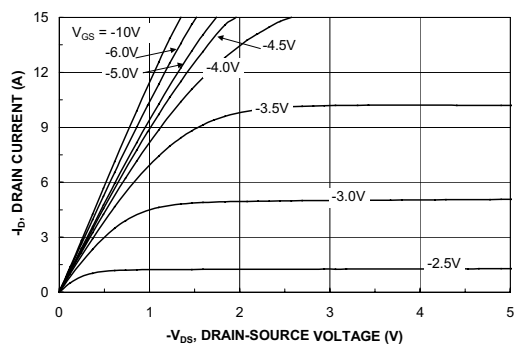


Figure 1. On-Region Characteristics.

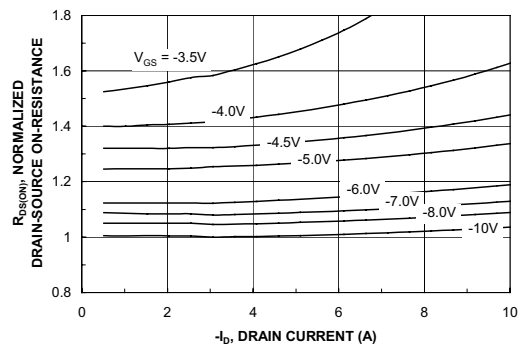


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

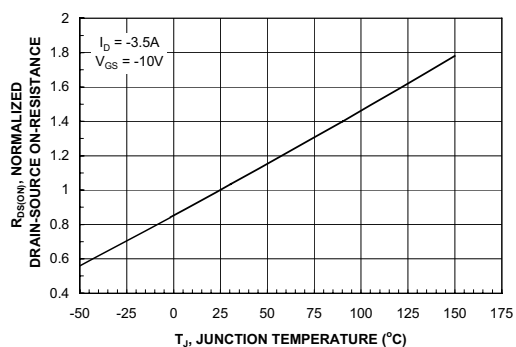


Figure 3. On-Resistance Variation with Temperature.

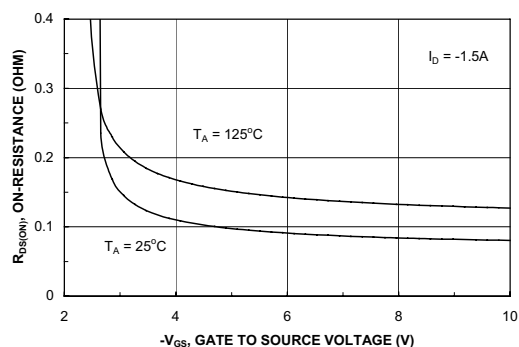


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

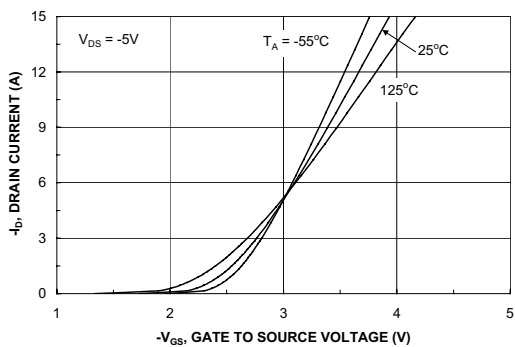


Figure 5. Transfer Characteristics.

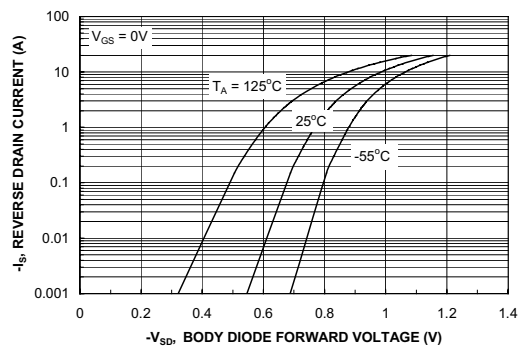


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

## Typical Characteristics: P-CH

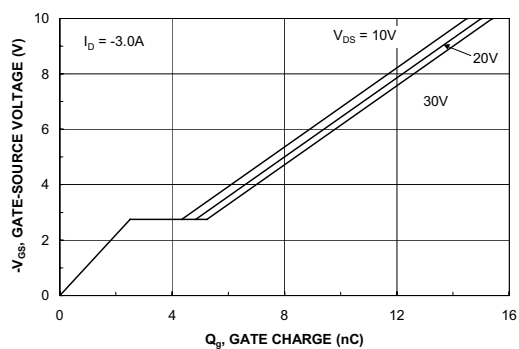


Figure 7. Gate Charge Characteristics.

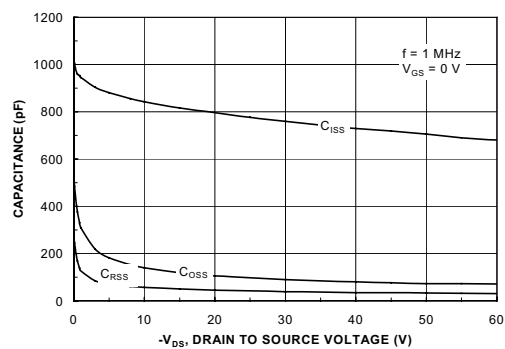


Figure 8. Capacitance Characteristics.

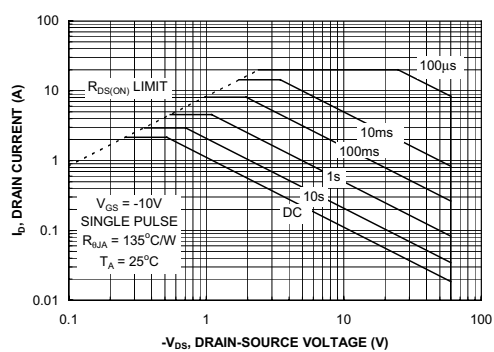


Figure 9. Maximum Safe Operating Area.

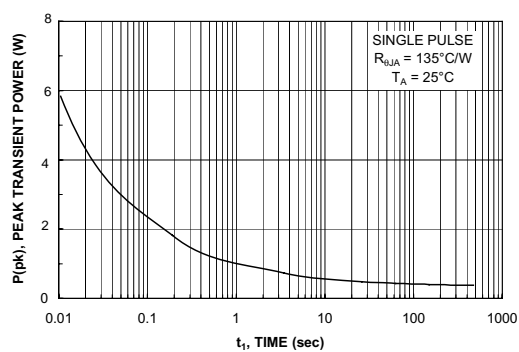


Figure 10. Single Pulse Maximum Power Dissipation.

## Typical Characteristics: N-CH

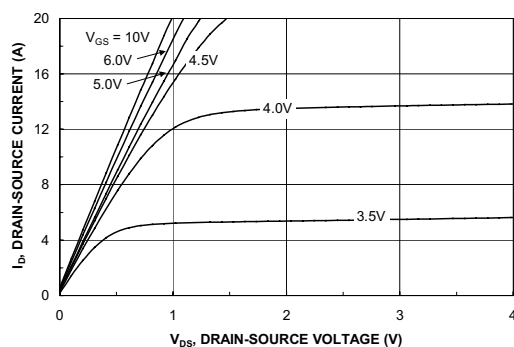


Figure 11. On-Region Characteristics.

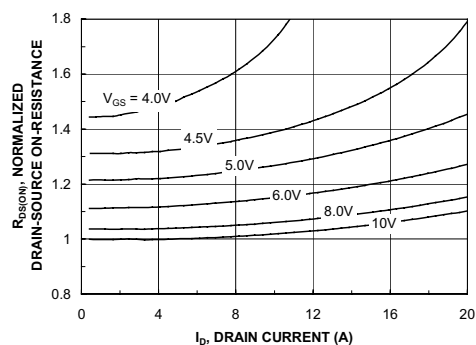


Figure 12. On-Resistance Variation with Drain Current and Gate Voltage.

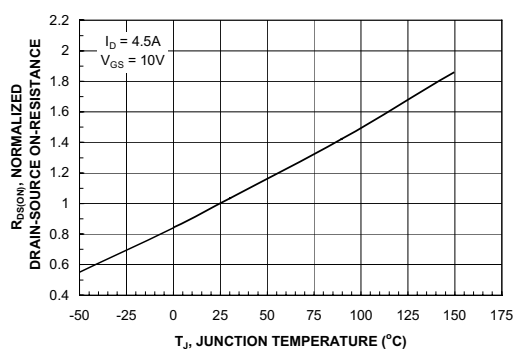


Figure 13. On-Resistance Variation with Temperature.

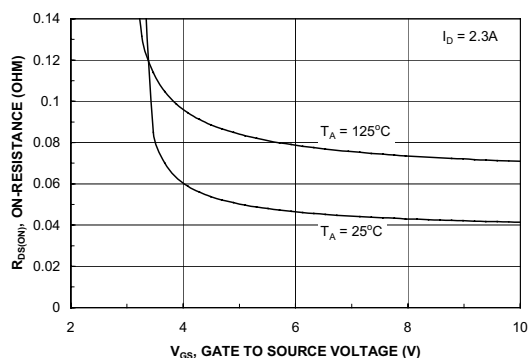


Figure 14. On-Resistance Variation with Gate-to-Source Voltage.

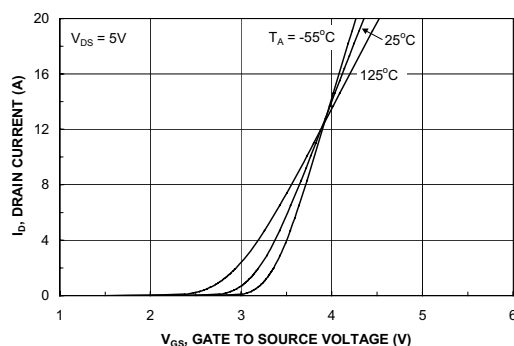


Figure 15. Transfer Characteristics.

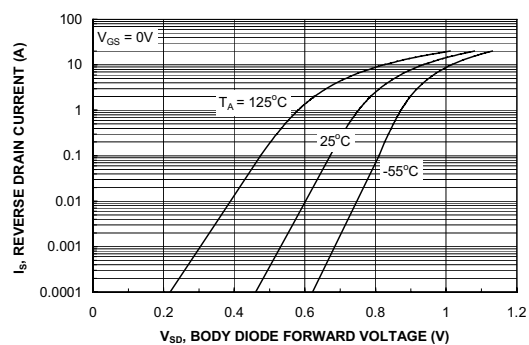


Figure 16. Body Diode Forward Voltage Variation with Source Current and Temperature.

## Typical Characteristics: N-CH

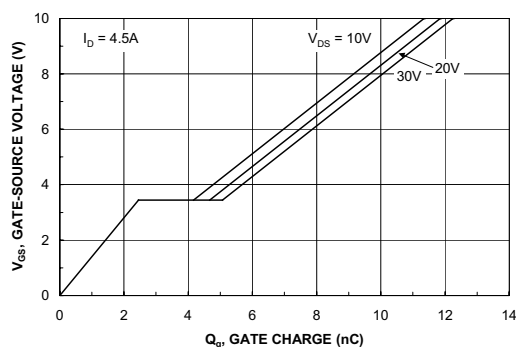


Figure 17. Gate Charge Characteristics.

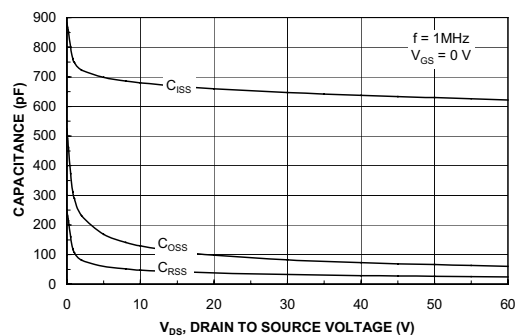


Figure 18. Capacitance Characteristics.

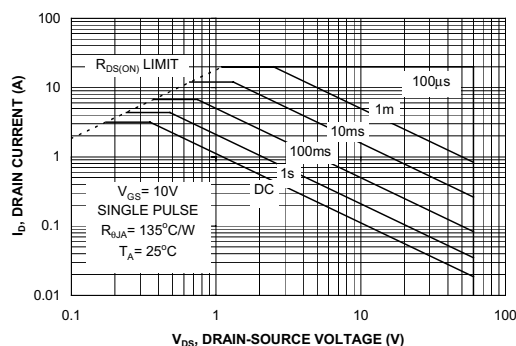


Figure 19. Maximum Safe Operating Area.

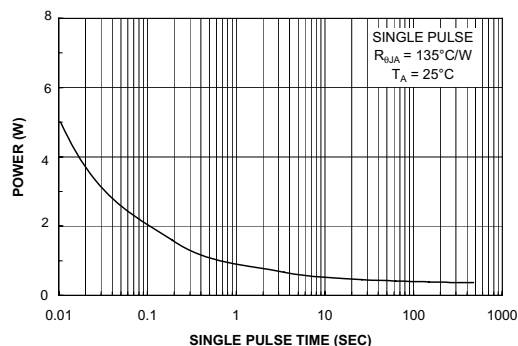


Figure 20. Single Pulse Maximum Power Dissipation.

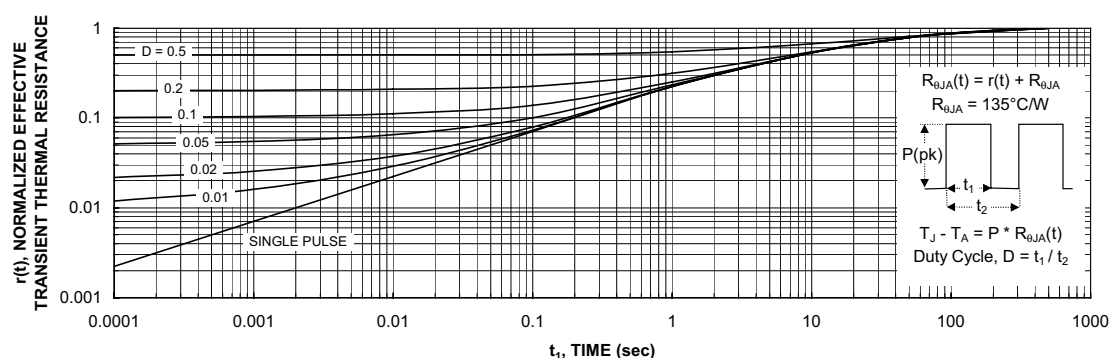
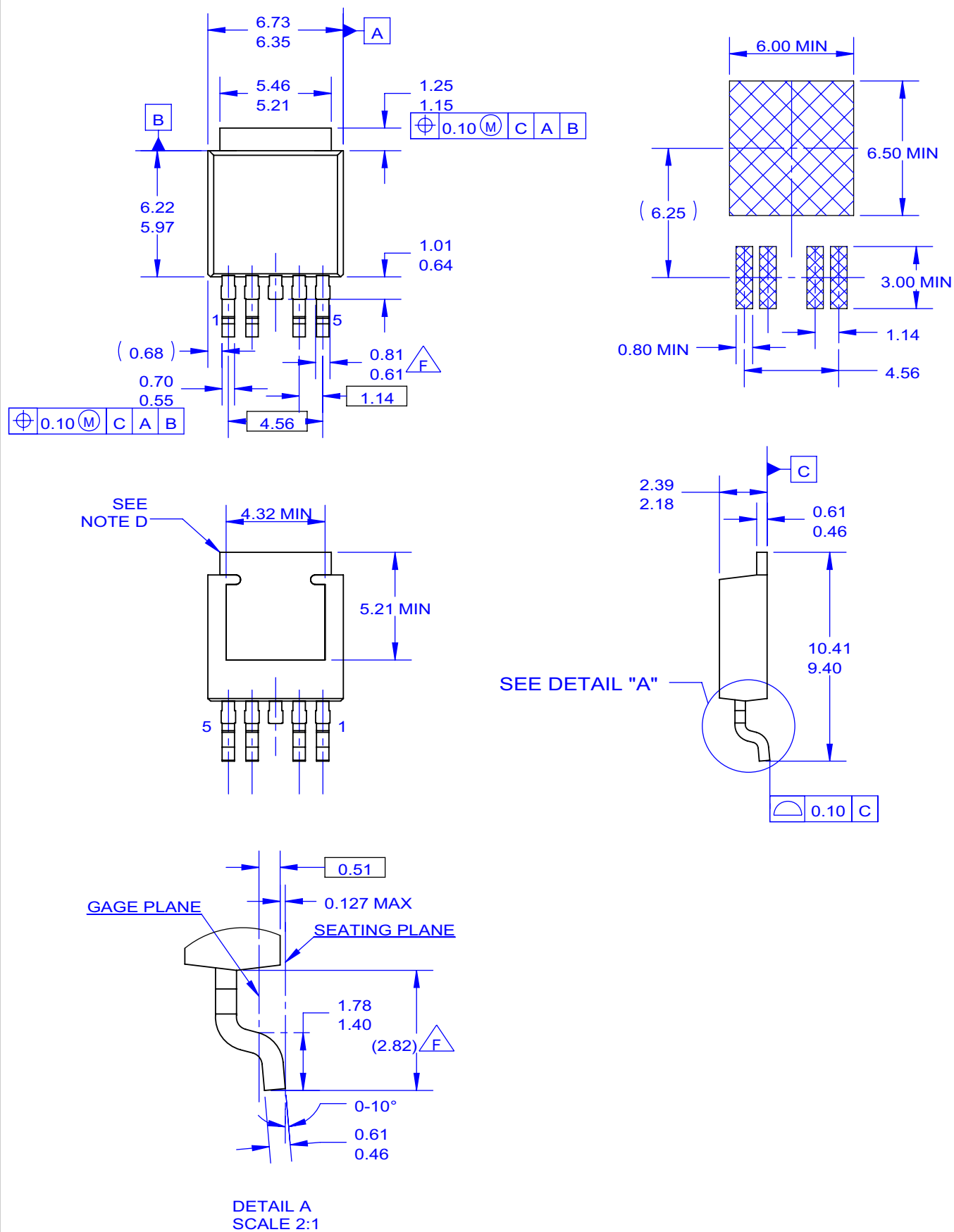


Figure 21. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c.  
Transient thermal response will change depending on the circuit board design.

# PACKAGE OUTLINE DIMENSIONS





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